

CLAIM AMENDMENTS

1. (previously presented) A copper interconnect comprising:
 - an impure copper seed layer derived from an impure copper source with a content of impurities that is deposited on a barrier layer, said barrier layer prevents substantial diffusion of copper through to an underlying insulating layer;
 - an impure copper derived from an impure copper source with a content of impurities that fills an opening in said underlying insulating layer that is deposited on said impure copper seed layer; and,

wherein material composition of said seed layer is substantially the same as material composition of said impure copper fill.
2. (original) A copper interconnect as in claim 1, wherein said copper source of said impure copper seed layer is equivalent to said copper source of said impure copper.
3. (original) A copper interconnect as in claim 1, wherein said impurity content comprises not more than 1.20% by weight and not less than or equal to 0.001% by weight of said at least one of said impure copper seed layer and said impure copper.
4. (original) A copper interconnect as in claim 1, wherein prior to deposition, said impure copper in said impure copper seed layer is substantially equivalent to said impure copper.

5. (original) A copper interconnect as in claim 1, wherein said copper in said impure copper source comprises impurities chosen from the group of Ag, As, C, Cd, Cl, Co, Cr, Fe, In, Mg, Mn, N, Ni, O, Pb, S, Sn, Tl, and Zn.

6. (withdrawn) A method for forming a copper interconnect, comprising the steps of:

depositing an impure copper seed layer derived from an impure copper seed source with a content of impurities on a barrier layer, said barrier layer prevents substantial diffusion of said copper through to an underlying insulating layer and lines an opening in said underlying insulating layer; and,

filling said opening with impure copper derived from an impure copper seed source with a content of impurities.

7. (withdrawn) A method as in claim 6, wherein said copper source of said impure copper seed layer is equivalent to said copper source of said impure copper.

8. (withdrawn) A method as in claim 6, wherein said impurity content comprises not more than 1.20% by weight and not less than or equal to 0.001% by weight of said at least one of said impure copper seed layer and said impure copper.

9. (withdrawn) A method as in claim 6, wherein said impure copper source comprises impurities chosen from the group of Ag, As, C, Cd, Cl, Co, Cr, Fe, In, Mg, Mn, N, Ni, O, Pb, S, Sn, Tl, and Zn.

10. (withdrawn) A method as in claim 6, wherein prior to deposition, said impure copper in said impure copper seed layer is substantially equivalent to said impure copper.

11. (withdrawn) A method as in claim 6, wherein said impure copper seed layer is deposited by at least one of sputtering, PVD, CVD, IPVD, and ALD.

12. (withdrawn) A method as in claim 6, further comprising the step of:
chemical mechanically polishing said impure copper seed layer, said barrier layer,
and said impure copper, until said impure copper seed layer, said barrier layer, and said
impure copper are planarized to said insulating layer.

13. (currently amended) A copper interconnect comprising:
an insulating layer that has an opening;
a barrier layer that prevents substantial diffusion of copper through to said
underlying insulating layer that is deposited on said underlying insulating layer and lines
said opening;
an impure copper seed derived from an impure copper seed source with a content
of impurity that is deposited on said barrier layer and fills said opening;
an impure copper derived from an impure copper source with a content of
impurities that fills said opening in said underlying insulating layer that is deposited on
said impure copper seed; and

wherein material composition of said seed layer impure copper seed is substantially the same as material composition of said impure copper fill.

14. (original) A copper interconnect as in claim 13, wherein said impurity content comprises not more than 1.20% by weight and not less than or equal to 0.001% by weight of said impure copper seed layer.

15. (original) A copper interconnect as in claim 13, wherein said impure copper from said impure copper seed source comprises impurities chosen from the group of Ag, As, C, Cd, Cl, Co, Cr, Fe, In, Mg, Mn, N, Ni, O, Pb, S, Sn, Tl, and Zn.

16. (withdrawn) A method for forming a copper interconnect, comprising the steps of:

depositing an insulating layer;
etching an opening in said insulating layer;
depositing a barrier layer that prevents copper diffusion through to said insulating layer, which lines said opening, in said insulating layer; and,
filling said opening with impure copper seed derived from an impure copper seed source with a content of impurities.

17. (withdrawn) A method as in claim 16, wherein said impurity content comprises not more than 1.20% by weight and not less than or equal to 0.001% by weight of said at least one of said impure copper seed.

18. (withdrawn) A method as in claim 16, further comprising the step of:
chemical mechanically polishing said impure copper seed and said barrier layer
until said barrier layer and said impure copper seed are planarized to said insulating layer.
19. (withdrawn) A method as in claim 16, wherein said impure copper seed source
comprises impurities chosen from the group of Ag, As, C, Cd, Cl, Co, Cr, Fe, In, Mg,
Mn, N, Ni, O, Pb, S, Sn, Tl, and Zn.
20. (withdrawn) A method as in claim 16, wherein said impure copper seed is
deposited by at least one of sputtering, PVD, CVD, IPVD, and ALD.